

<Market Research Report>

Technology & Market Trends Report on EMI Shielding Film -2023-

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Focal points of survey



- 1. Global market size of EMI shielding film (Y2022)
 - -Market breakdown by application, by type of film, and by manufacturers
- 2. Market size and forecasts for EMI shielding films (Y2021-2032)
 - -Market forecast of EMI shielding film by application, and by type of film
- 3. EMI shielding film manufacturers' entry products, business trends, development trends, supply relations, etc.
- 4. Trend of application (Adoption trend, technology & market trends, etc.)
 - -Smartphone, Tablet PC/others, Automotive, and Telecommunication base stations
- 5. Manufacturers' Case Studies of EMI shielding film

Surveyed Products/Classification & Surveyed Manufacturers

1.Surveyed Products (EMI Shielding Film) / Classification

EMI shielding film mainly used in electronic devices such as FPC/rigid flexible boards, PCBs, and parts.

- 1) Form/structure type
 - -Film/sheet: Thin metal (vapor deposition/plating, and ultra-thin metal foil type), and Conductive resin type
 - -Adhesive tape: Thin metal foil type, Conductive fiber, and others
- 2) Application
- -Smartphone: Smartphone, Cellular phone
- -Tablet PC/others: Tablet PC, Notebook PC, Smartwatch, Digital camera, and other small electronic equipment
- -Automotive: Electronic devices for Infotainment, for Sensor, for LED, for Switch, and for Powertrain
- -Telecom/Industrial/others: Telecommunication base station/facility, FA equipment/Inspection equipment, Medical equipment, and others

2. Surveyed Manufacturers

Surveyed	products	Manufacturers
EMI shielding film	Film/she et	Seiwa Electric Mfg., TATSUTA Electric Wire and Cable, TOYOCHEM, Panasonic, Guangdong Zhongchen Industrial, Guangzhou Fangbang Electronics, InkTek, Shenzhen KNQ Technology, Suzhou Chengbangdali Material Technology, Youlchon, ZhengyeTechnology, etc.
	Adhesiv e tape	Kitagawa Industries, Seiwa Electric Mfg., Seiren, Takeuchi Industry, TATSUTA Electric Wire and Cable, DIC, Dexerials, Teraoka Seisakusho, TOKIN, Nitto Denko, 3M Company, ICH, Meixin New Material, Parker Hannifin, Suzhou Chengbangdali Material Technology, tesa Group, Wida Tech Printing, etc.
FPC/Rigid-flex PCB/Assembly		Zhen Ding Technology Holding, Nippon Mektron, Suzhou Dongshan Precision Manufacturing, FLEXium Interconnect, BH, Fujikura, Murata Manufacturing Company, Sumitomo Electric Printed Circuits, etc.

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Sample (1)

Samsung

Oppo, vivo, Xiaomi and other Chinese maker

EMS



Summary

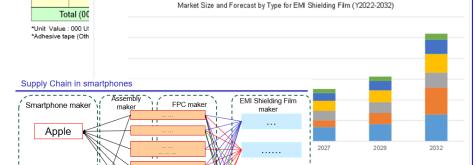
Market Size and Forecast by Type for EMI Shielding Film

				2023	2025	2027	2029	2032	CAGR
Film/ sheet	Thin metal	VD/plating							
Silect		UT metal foil							
	Conductive res								
		Subtotal							
Adhesive	Thin metal foil								
tape	Conduc	tive fiher							

As For Smartphone, Market Size and Forecast of EMI Shielding Film

				2022	2023	2025	2027	2029	2032	CAGR	
Uni	Film/	Thin	VD/plating	ZUZZ	2023	2020	2021	2023	2002	ONOR	
Adh	sheet	metal	UT metal foil								
		Condu	ctive resin								
			Subtotal								
	Adhesive Thin As For Automotive, Market Size and Forecast of EMI Shielding Fil										
		Other	[Graph	As For Auton	notive, Marke	et Size and F	orecast by Ty	pe for EMI S	hielding Film	ı -Value Ba	

se-]



... Group

Chapter 1, Technology and Market Trend of EMI Shielding Film

- 1. Definition and role of the product under study (EMI Shielding Film)
- 2) Roles of EMI shielding films:
- (1) Prevents malfunctions and performance degradation caused by
- (2) Prevent leakage of
- (3) Stabilize

4. Form/structure and constituent materials of EMI Shielding Films



2) Adhesive tape

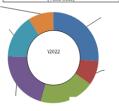
				С	Constituent material					
Туре	Structure (cross section figure)		Base resir	1	Co	nductive f	iller			
	*figure: Schematic diagram for double side type	Epoxy	Urethane	Others	Ag coated Cu	Ag	Others	Others		
Thin metal foil	Adhesive (base resin) Thin metal foil Conductive filler			M ()				Metal foil:		
Conductiv e fiber	Adhesive (base resin) Conductive cloth / fiber inductive filler			M ()				Conductive fiber (cloth/non woven fabric): plated fiber plated fiber etc.		
Others (Conductive	Adhesive (base resin)							-		

6. Adoption status of EN

Applicat ion	FPC/FPC mo	odule parts	Thin VD/plating	Film/ metal UT r	Others (Conductive resin, Conductive	uctive Adhesive (base resin)										-	
	Display modu Camera mod Dock flex/Sui Antenna	ule			foam-base type, etc.)				tive filler								
Tablet PC	connection module	For other antenna															
		play/Backlight, etc.)															
	Battery modu	lattery module					_			_							
		Switch module									—						
	Others	Speaker FPC	_							——I	ı of EMI Shielding Film (Y2022)						
_		Other sensor FPC	-	_			_										
		Hinge wiring	_														
	Connection	Sub board	_	_			_			re	eakdown	(Value)	Y20221				
ok PC	FPC	Mechanical parts					_	_			Teakdown (value) 12022]						
		Camera															
	Display modu	ule (for monitor)										Market	Share hy T	me for FMI	Shielding Fil	m in V2022	
Digital	Connection	Between boards										make	Office by I	(Value bas		12022	
camera	FPC	Sensors									(Yalde base)				~,		
		Mechanical parts															

14. Changes and forecasts in the market size of EMI Shielding Film by application (Y2021-2032)

[Graph Changes and forecasts in the market size by type for Smartphone of EMI Shielding Film -Value Base-] Changes and forecasts in the market size by type for Smartphone of EMI Shielding Film (Y2021-2032)



Sample (2)

JMS

Chapter 2, Trends of Applications

Adoption status of FPCs and EMI Shielding Films used in smartphones





7. Market trends of FPCs for smartphones

1) Changes and forecasts in the market size (Y2021-2032)

			2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	CAGR	
Example of adhesive ta	Display N	Module														
EMI shielding film used	Camera Module															
smartphones is shown.	Dock flex	c, sub board														
It is mainly used for		for 5G mmW														
. Technology and mar	ket tre	ends of majo	r FPC	s / A	doptio	on tre	nds o	f EMI	shiel	ding f	films					
											_					
*The adoption of EMI sh	*The adoption of EMI shielding film is															
													_	_	_	

[Technology trend of device, FPC and EMI shielding in display modules]

			Y2022	Y2023	Y2025	Y2027	Y2029	Y2032	Remarks
technolog	Number of (Advanced								
	OLED ado	ption ratio							
FPC		SS or DS							
		ML or R/F							
	Supports high speed								
	FPC base material								
	Shield cha	racteristics							
EMI shielding films/sheet	Others								

Chapter 3, Manufacturers' Case Studies

Company Profile

Head office location									
Capital	Entry Status by Type and EMI Shielding Film Products								
Number of employees =									
Business outline	Product type			Market entry status	Main product / number				
Annual sales	Film/sheet	Thin metal	VD/plating		SF-PC5000-C,				
EMI shielding film sales (Estimated by JMS)				Y					
(Estimated by Jivis)			UT metal foil						
		Conductive resin							
[Summary]	Adhesive tape	Thin metal foil							
*Tatsuta Electric Wire and Ca		Conductive fiber							

Overview of EMI Shielding Film Products

Product series / number	Structure	Product overview			eviations> VD: vapor deposition, UT: ultra-thin F-FT series: High flexibility, SF-CA: Adhesive tape			
SF-PC	Transfer film Protection layer (ZL) 2d protection L 2nd protection L	They are						
Shielding layer	"The shielding effect" "The main applicable 1) Production site / capacity							
	Anisotropic conductive adhesion layer		Production site	Capacity	Production item			
SF-PC Fundamental Interference SF-PC	*They are		-					
	*The layer structure		-					
		*The protective laye *powde *Press conditions (f *The film thickness		-	SF-PC5000, SF-PC5500, SF-PC5600 and others			
			Total	SQM/month				
		"The shielding effec "The main application						

Sales Status/Sales Breakdown

3) Sales Breakdown (Y2022)

for smartphone by

ewly developed products, ...

the plant

٥, ٥		J. Oan			-,					, , , , , ,	
				Smartphone		Tablet PC/others	Automotive	Telecom/Indu strial/others	Total		
		Thin	VD/plating								
me	et	metal	UT metal foil								
		Conductive resin									
		Sı	ubtotal								
	Adhesive	Thin meta	l foil								
	tape	Conductive fiber Others			$\overline{}$					1	٦.
					Types of TATCLITA Floatric						
		Subtotal			Example of TATSUTA Electric						
	Total(000 SQM)			•							
Value	Film/she	Thin	VD/plating	Wire and Cable Co., L					Ltd.	1	
	et	metal	UT metal foil								
		Conductiv	e resin								-
		Subtotal									
	Adhesive Thin metal foil										
	tape	Conductive fiber									0
		Others									0
		Subtotal								1	
	Tetal(000LICD)								1		

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*Account Name: Japan Marketing Survey Co., Ltd.	

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